

L Number	Hits	Search Text	DB	Time stamp
1	132746	connector and cable	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/28 21:59
2	2331891	((integrated adj circuit) ic semiconductor die chip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/28 22:00
3	28451	((connector and cable) and ((integrated adj circuit) ic semiconductor die chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/28 22:01
4	6872	((substrate carrier) and (pcb board cb pb ((printed circuit) adj3 board)) and ((connector and cable) and ((integrated adj circuit) ic semiconductor die chip))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/28 22:02
5	3280	((substrate carrier) and (pcb board cb pb ((printed circuit) adj3 board)) and ((connector and cable) and ((integrated adj circuit) ic semiconductor die chip))) and (package packaging packaged)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/28 22:03
6	1979	((substrate carrier) and (pcb board cb pb ((printed circuit) adj3 board)) and ((connector and cable) and ((integrated adj circuit) ic semiconductor die chip))) and (package packaging packaged)) and (trace wiring)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/28 22:03

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6	1979	((substrate carrier) and (pcb board cb pb ((printed circuit) adj3 board)) and ((connector and cable) and ((integrated adj circuit) ic semiconductor die chip))) and (package packaging packaged)) and (trace wiring)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/28 22:03
7	1867	((substrate carrier) and (pcb board cb pb ((printed circuit) adj3 board)) and ((connector and cable) and ((integrated adj circuit) ic semiconductor die chip))) and (package packaging packaged)) and (trace wiring)) and (signaling signal)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/28 22:04
8	1610	((substrate carrier) and (pcb board cb pb ((printed circuit) adj3 board)) and ((connector and cable) and ((integrated adj circuit) ic semiconductor die chip))) and (package packaging packaged)) and (trace wiring)) and (signaling signal)) and method and system	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/28 22:04